

# P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ)			
- 60	0.046 at V <sub>GS</sub> = - 10 V	- 35	26			
- 50	0.058 at V <sub>GS</sub> = - 4.5 V	- 30	20			

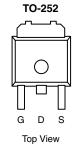
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

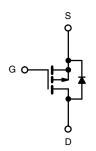


#### **APPLICATIONS**

- · High Side Switch for Full Bridge Converter
- DC/DC Converter for LCD Display



Drain Connected to Tab



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $(T_A = 2)$	25 °C, unless otherw	rise note)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	- 60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	1 V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	- 35		
Continuous Diam Current (1) = 130 O)	T <sub>C</sub> = 125 °C	] <sup>'D</sup> [	- 25	A	
Pulsed Drain Current	I <sub>DM</sub>	- 100	A		
Avalanche Current, Single Pulse	L = 0.1 mH		- 22		
Repetitive Avalanche Energy, Single Pulse <sup>a</sup>	L = 0.1 IIII	E <sub>AS</sub>	24.2	mJ	
Dower Discinstics	T <sub>C</sub> = 25 °C	P <sub>D</sub>	38.5 <sup>c</sup>	W	
Power Dissipation	T <sub>A</sub> = 25 °C	1 'D	2.3 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marrian un lumation to Auchionab	t ≤ 10 s	R <sub>thJA</sub>	17	21		
Maximum Junction-to-Ambient <sup>D</sup>	Steady State		45	55	°C/W	
Maximum Junction-to-Case		R <sub>thJC</sub>	2.7	3.25		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. See SOA curve for voltage derating.
- d. Based up on  $T_C$  = 25 °C.



Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			- 50	μΑ	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ} \text{ C}$	<sub>S</sub> = 0 V, T <sub>J</sub> = 150 ° C		- 125		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A		0.046			
Drain-Source On-State Resistance <sup>a</sup>	Booker	$V_{GS} = -10 \text{ V}, I_D = -10 \text{ A}, T_J = 125 \text{ °C}$		0.095		Ω	
Didin-Source On-State nesistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A, T <sub>J</sub> = 150 °C		0.115			
		$V_{GS} = -4.5 \text{ V}, I_D = -5 \text{ A}$		0.058			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 10 A		22		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			1900		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		130			
Reverse Transfer Capacitance	C <sub>rss</sub>			90			
Total Gate Charge <sup>c</sup>	Qg			26	40		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		4.5		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		7		Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	15		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V, R}_{L} = 3 \Omega$		9	15		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -19 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		65	100	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			30	45		
Drain-Source Body Diode and Charact	eristics (T <sub>C</sub> = 2	5 °C) <sup>b</sup>					
Continuous Current	I <sub>S</sub>				- 20		
Pulsed Current	I <sub>SM</sub>				- 30	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 19 A, V <sub>GS</sub> = 0 V		- 1	- 1.5	V	
Reverse Recovery Time t <sub>rr</sub>		I <sub>F</sub> = - 19 A, di/dt = 100 A/μs 41		61	ns		

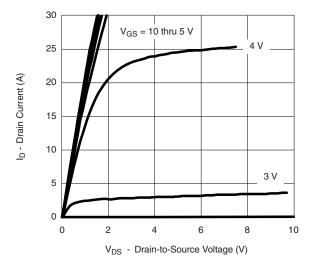
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

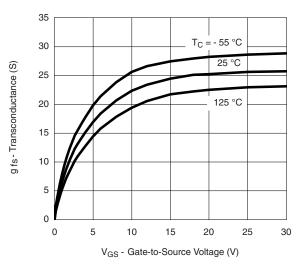
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



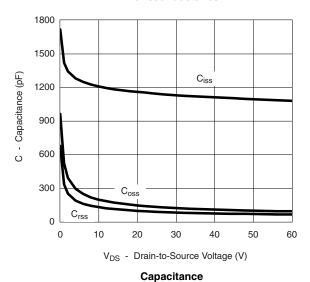
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### **Output Characteristics**

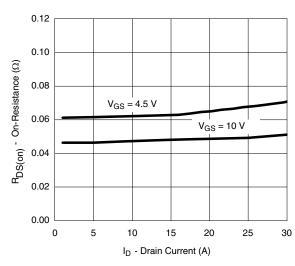


#### Transconductance

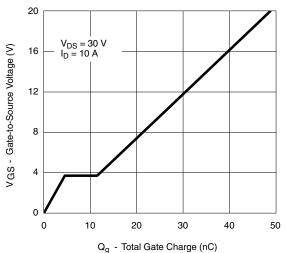


30 25 I<sub>D</sub> - Drain Current (A) 20 15 10 T<sub>C</sub> = 125 °C 5 25 °C 55 °C 0 0.0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0 V<sub>GS</sub> - Gate-to-Source Voltage (V)

#### Transfer Characteristics



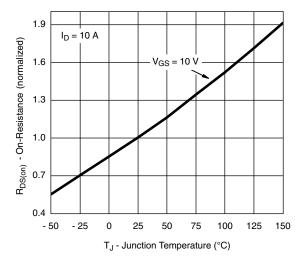
#### On-Resistance vs. Drain Current



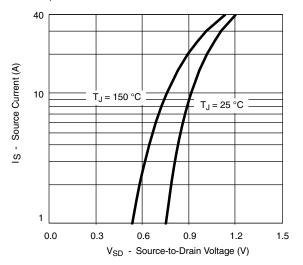
**Gate Charge** 



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

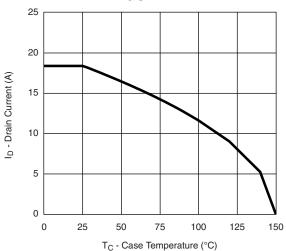


On-Resistance vs. Junction Temperature

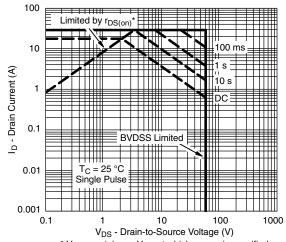


Source-Drain Diode Forward Voltage

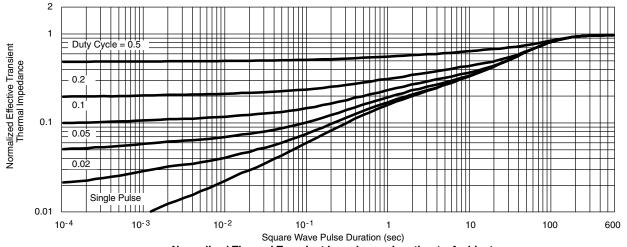
#### THERMAL RATINGS



Maximum Drain Current vs. Case Temperature



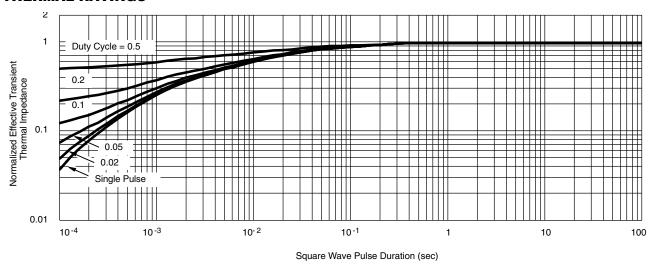
\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which r<sub>DS(on)</sub> is specified **Safe Operating Area** 



Normalized Thermal Transient Impedance, Junction-to-Ambient



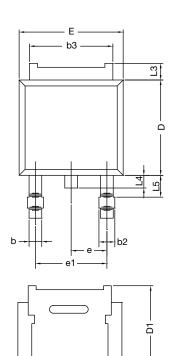
#### **THERMAL RATINGS**

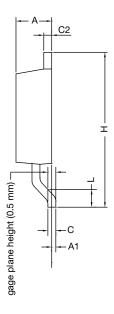


Normalized Thermal Transient Impedance, Junction-to-Case



# **TO-252AA Case Outline**





	MILLIN	METERS	INCHES				
DIM.	MIN.	MAX.	MIN.	MAX.			
А	2.18	2.38	0.086	0.094			
A1	-	0.127	-	0.005			
b	0.64	0.88	0.025	0.035			
b2	0.76	1.14	0.030	0.045			
b3	4.95	5.46	0.195	0.215			
С	0.46	0.61	0.018	0.024			
C2	0.46	0.89	0.018	0.035			
D	5.97	6.22	0.235	0.245			
D1	4.10	-	0.161	-			
Е	6.35	6.73	0.250	0.265			
E1	4.32	-	0.170	-			
Н	9.40	10.41	0.370	0.410			
е	2.28	2.28 BSC		BSC			
e1	4.56	4.56 BSC		BSC			
L	1.40	1.78	0.055	0.070			
L3	0.89	1.27	0.035	0.050			
L4	-	1.02	-	0.040			
L5	1.01	1.52	0.040	0.060			
ECN: T16-0	ECN: T16-0236-Rev. P. 16-May-16						

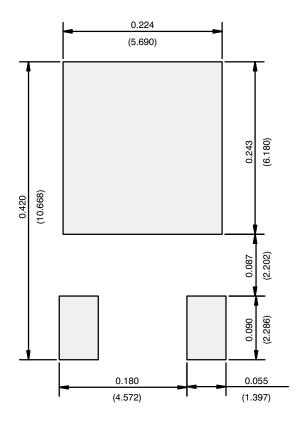
ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347

#### Notes

• Dimension L3 is for reference only.



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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